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Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild_questions@onsemi.com.

FAIRCHILD SEMICONDUCTOR®

September 2009

NC7SZ157
TinyLogic® UHS 2-Input Non-Inverting Multiplexer

Features

- Broad V_{CC} Operating Range: 1.65V to 5.5V
- Ultra High-Speed
- Power Down High-Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5V to 3V Translation
- Proprietary Noise/EMI Reduction Circuitry
- Ultra-Small MicroPak™ Packages
- Space-Saving SC70 Package

Description

The NC7SZ157 is a single, high performance, 2-to-1 CMOS non-inverting multiplexer from Fairchild's Ultra-High Speed series of TinyLogic®. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over the 1.65V to 5.5V V_{CC} operating range. The inputs and outputs are high impedance when V_{CC} is 0V. Inputs tolerate voltages up to 5.5V independent of V_{CC} operating range.

Ordering Information

Part Number	Top Mark	Eco Status	Package	Packing Method
NC7SZ157P6X	ZF7	RoHS	6-Lead SC70, EIAJ SC-88, 1.25mm Wide	3000 Units on Tape & Reel
NC7SZ157L6X	B9	RoHS	6-Lead MicroPak™, 1.00mm Wide	5000 Units on Tape & Reel
NC7SZ157FHX	B9	Green	6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

For Fairchild's definition of Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs_green.html.

Connection Diagrams

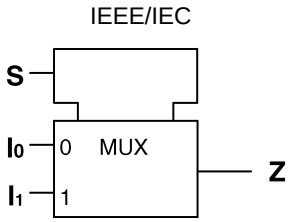


Figure 1. Logic Symbol

Pin Configurations

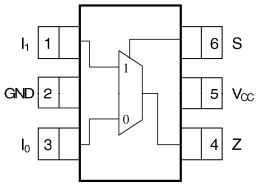


Figure 2. SC70 (Top View)

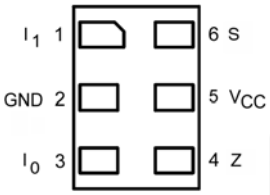


Figure 3. MicroPak™ (Top Through View)

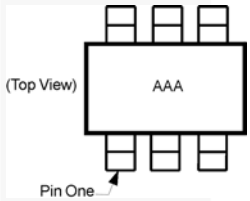


Figure 4. Pin 1 Orientation

Notes:
1. AAA represents product code top mark (*see Ordering Information*).
2. Orientation of top mark determines pin one location.
3. Reading the top mark left to right, pin one is the lower left pin.

Pin Definitions

Pin # SC70	Pin # MicroPak	Name	Description
1	1	I_1	Data Input
2	2	GND	Ground
3	3	I_0	Data Input
4	4	Z	Output
5	5	V_{CC}	Supply Voltage
6	6	S	Control Input

Function Table

Inputs			Output
S	**I_1**	**I_0**	**$Z = (I_0) \bullet (S) + (I_1) \bullet (S)$**
L	X	L	L
L	X	H	H
H	L	X	L
H	H	X	H

H = HIGH Logic Level

L = LOW Logic Level

X = Don't' Care

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V_{CC}	Supply Voltage		-0.5	7.0	V
V_{IN}	DC Input Voltage		-0.5	7.0	V
V_{OUT}	DC Output Voltage		-0.5	7.0	V
I_{IK}	DC Input Diode Current	$V_{IN} \leq 0.5V$		-50	mA
I_{OK}	DC Output Diode Current	$V_{OUT} \leq -0.5V$		-50	mA
I_{OUT}	DC Output Current			±50	mA
I_{CC} or I_{GND}	DC V_{CC} or Ground Current			±50	mA
T_{STG}	Storage Temperature Range		-65	+150	°C
T_J	Junction Temperature Under Bias			+150	°C
T_L	Junction Lead Temperature (Soldering, 10 Seconds)			+260	°C
P_D	Power Dissipation at +85°C	SC70-6		180	mW
		MicroPak-6		130	
		MicroPak2-6		120	
ESD	Human Body Model, JEDEC:JESD22-A114			4000	V
	Charge Device Model, JEDEC:JESD22-C101			2000	

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V_{CC}	Supply Voltage Operating		1.65	5.50	V
	Supply Voltage Data Retention		1.50	5.50	
V_{IN}	Input Voltage		0	5.5	V
V_{OUT}	Output Voltage		0	V_{CC}	V
T_A	Operating Temperature		-40	+85	°C
t_r, t_f	Input Rise and Fall Times	V_{CC} at 1.8V ± 0.15V, 2.5V ± 0.2V	0	20	ns/V
		V_{CC} at 3.3V ± 0.3V	0	10	
		V_{CC} at 5.0V ± 0.5V	0	5	
θ_{JA}	Thermal Resistance	SC70-6		350	°C/W
		MicroPak-6		500	
		MicroPak2-6		560	

DC Electrical Characteristics

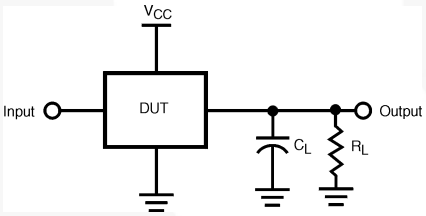
Symbol	Parameter	V_{CC}	Conditions		T_A=+25°C			T_A=-40 to +85°C		Units
					Min.	Typ.	Max.	Min.	Max.	
V_{IH}	HIGH Level Input Voltage	1.65 to 1.95			0.75V_{CC}			0.75V_{CC}		V
		2.30 to 5.50			0.70V_{CC}			0.70V_{CC}		
V_{IL}	LOW Level Input Voltage	1.65 to 1.95					0.25V_{CC}		0.25V_{CC}	V
		2.30 to 5.50					0.30V_{CC}		0.30V_{CC}	
V_{OH}	HIGH Level Output Voltage	1.65	V_{IN}=V_{IL} or V_{IH}	I_{OH}= -100µA	1.55	1.65		1.55		V
		2.30			2.20	2.30		2.20		
		3.00			2.90	3.00		2.90		
		4.50			4.40	4.50		4.40		
		1.65	V_{IN}=V_{IL} or V_{IH}	I_{OH}= -4mA	1.29	1.52		1.29		
		2.30		I_{OH}= -8mA	1.90	2.15		1.90		
		3.00		I_{OH}= -16mA	2.40	2.80		2.40		
		3.00		I_{OH}= -24mA	2.30	3.68		2.30		
		4.50		I_{OH}= -32mA	3.90	4.20		3.80		
V_{OL}	LOW Level Output Voltage	1.65	V_{IN}=V_{IL} or V_{IH}	I_{OL}= 100µA		0	0.10		0.10	V
		2.30				0	0.10		0.10	
		3.00				0	0.10		0.10	
		4.50				0	0.10		0.10	
		1.65	V_{IN}=V_{IL} or V_{IH}	I_{OL}= 4mA		0.08	0.24		0.24	V
		2.30		I_{OL}= 8mA		0.10	0.30		0.30	
		3.00		I_{OL}= 16mA		0.15	0.40		0.40	
		3.00		I_{OL}= 24mA		0.22	0.55		0.55	
		4.5		I_{OL}= 32mA		0.22	0.55		0.55	
I_{IN}	Input Leakage Current	0 to 5.50	V_{IN}=5.5V, GND				±0.1		±1	µA
I_{OFF}	Power Off Leakage Current	0	V_{IN} or V_{OUT}=5.5V				1		10	µA
I_{CC}	Quiescent Supply Current	1.65 to 5.50	V_{IN}=5.5V, GND						10	µA

AC Electrical Characteristics

Symbol	Parameter	V_{CC}	Conditions	T_A=+25°C			T_A=-40 to +85°C		Units	Figure
				Min.	Typ.	Max.	Min.	Max.		
t_{PLH}, t_{PHL}	Propagation Delay S to Z	1.80 ± 0.15	C_L=15pF, R_L=1MΩ,	2.5	6.0	11.5	2.5	12.0	ns	Figure 5 Figure 6
		2.50 ± 0.20		1.2	3.5	6.1	1.2	6.5		
		3.30 ± 0.30		0.8	2.6	4.1	0.8	4.5		
		5.00 ± 0.50		0.5	1.9	3.2	0.5	3.5		
	Propagation Delay I_n to Z	1.80 ± 0.15	C_L=15pF, R_L=1MΩ,	2.5	5.9	10.0	2.5	10.5		
		5.00 ± 0.50		1.2	3.5	5.8	1.2	6.1		
		3.30 ± 0.30		0.8	2.6	3.9	0.8	4.2		
		5.00 ± 0.50		0.5	1.9	3.1	0.5	3.3		
	Propagation Delay S to Z	3.30 ± 0.30	C_L=50pF, R_L=500Ω,	1.2	3.2	4.8	1.2	5.2		
		5.00 ± 0.50		0.8	2.4	3.8	0.8	4.1		
	Propagation Delay I_n to Z	3.30 ± 0.30	C_L=50pF, R_L=500Ω,	1.2	3.2	4.6	1.2	5.0		
		5.00 ± 0.50		0.8	2.4	3.7	0.8	4.0		
C_{IN}	Input Capacitance	0.00			2				pF	
C_{PD}	Power Dissipation Capacitance(4)	3.30			14				pF	Figure 7
		5.00			17					

Note:

4. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression: $I_{CCD}=(C_{PD})(V_{CC})(f_{IN})+(I_{CC}static)$.



Note:

5. C_L includes load and stray capacitance. Input PRR=1.0MHz, t_w=500ns.

Figure 5. AC Test Circuit

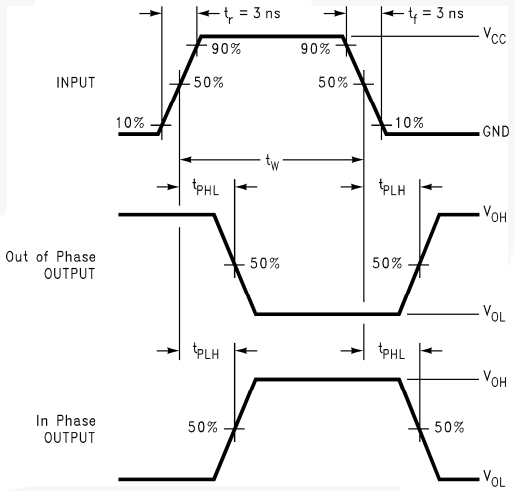
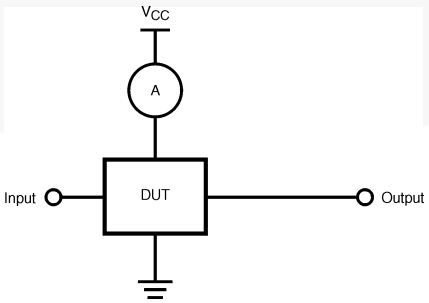


Figure 6. AC Waveforms



Note:

6. Input=AC Waveform; PRR=Variable; Duty Cycle=50%.

Figure 7. I_{CCD} Test Circuit

Physical Dimensions

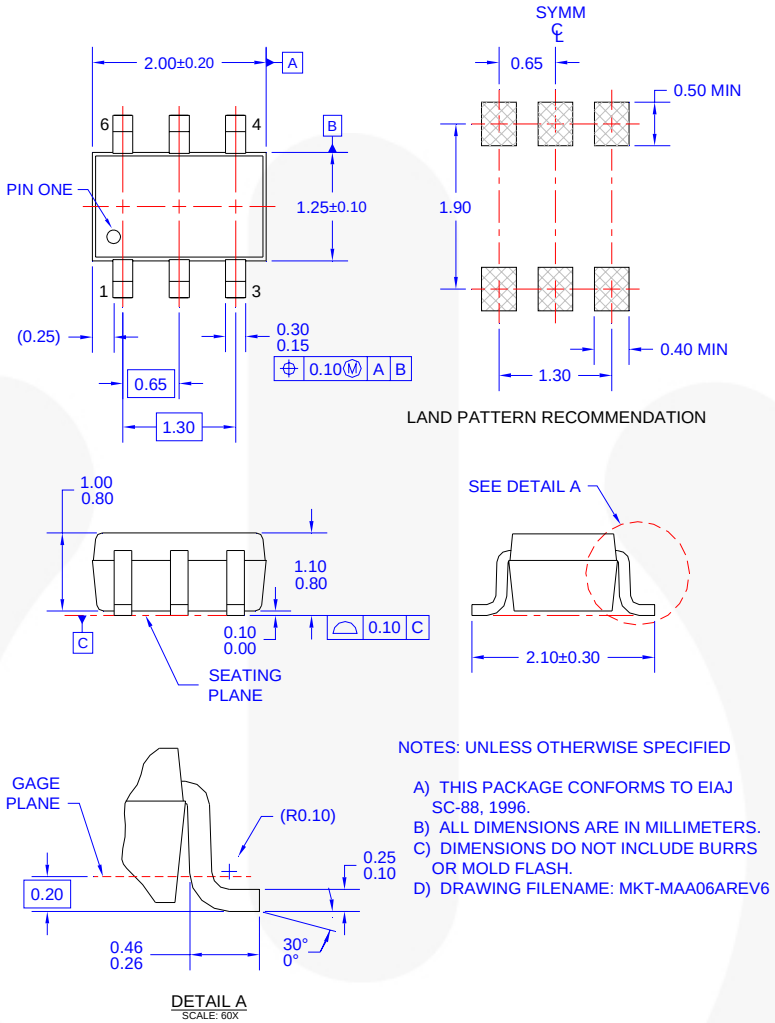


Figure 8. 6-Lead, SC70, EIAJ SC-88, 1.25mm Wide

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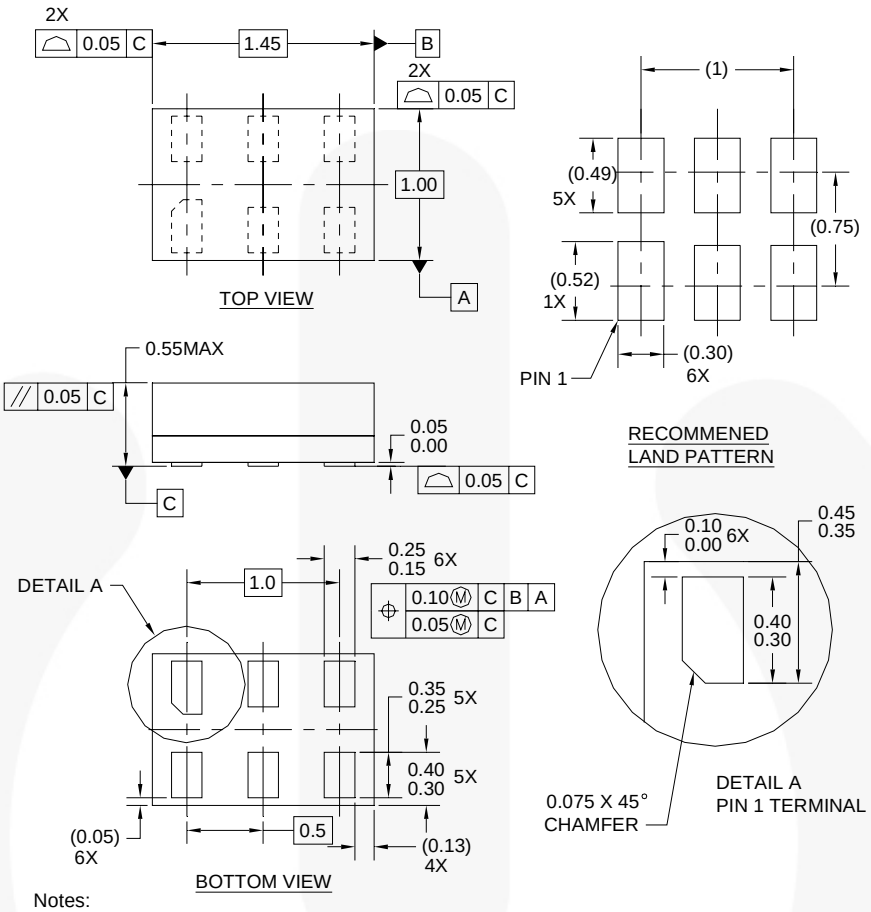
Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications:
http://www.fairchildsemi.com/products/analog/pdf/sc70-6_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
P6X	Leader (Start End)	125 (Typical)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions



Notes:

1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06AREVC

Figure 9. 6-Lead, MicroPak™, 1.0mm Wide

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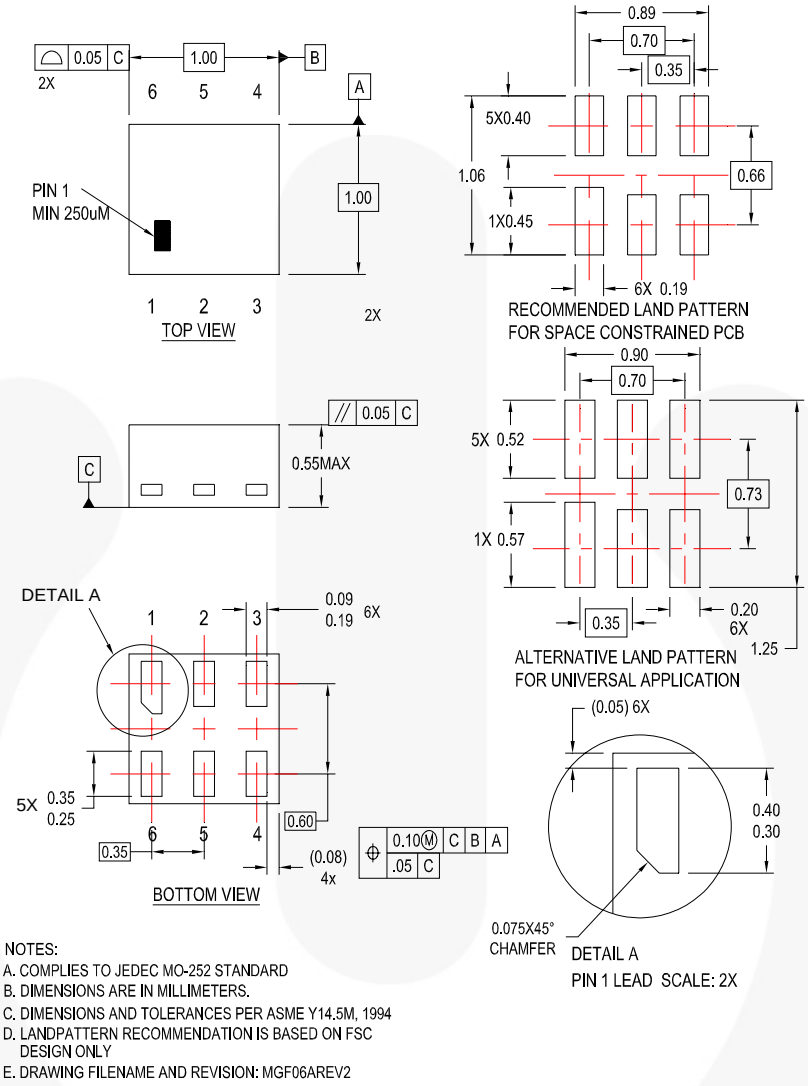
Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications:
http://www.fairchildsemi.com/products/logic/pdf/micropak_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
L6X	Leader (Start End)	125 (Typical)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions



NOTES:
A. COMPLIES TO JEDEC MO-252 STANDARD
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
D. LANDPATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY
E. DRAWING FILENAME AND REVISION: MGF06AREV2

Figure 10. 6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch

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Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications:
http://www.fairchildsemi.com/packaging/MicroPAK2_6L_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
FHX	Leader (Start End)	125 (Typical)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

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GTO™
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2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I43

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